- Designed for Complementary Use with the TIP34 Series
- 80 W at 25°C Case Temperature
- 10 A Continuous Collector Current
- 15 A Peak Collector Current
- Customer-Specified Selections Available

SOT-93 PACKAGE (TOP VIEW) B 1 C 2 3

Pin 2 is in electrical contact with the mounting base.

MDTRAA

absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING			VALUE	UNIT	
	TIP33		80		
Collector-base voltage (I _F = 0)	TIP33A	V	100	V	
Collector-base voltage (I _E = 0)	TIP33B	V _{CBO}	120	V	
	TIP33C		140		
	TIP33		40		
Collector-emitter voltage (I _B = 0)	TIP33A	V	60	V	
	TIP33B	V _{CEO}	80		
	TIP33C		100		
Emitter-base voltage		V _{EBO}	5	V	
Continuous collector current		I _C	10	Α	
Peak collector current (see Note 1)			15	Α	
Continuous base current			3	Α	
Continuous device dissipation at (or below) 25°C case temperature (see Note 2)			80	W	
Continuous device dissipation at (or below) 25°C free air temperature (see Note 3)			3.5	W	
Unclamped inductive load energy (see Note 4)			62.5	mJ	
Operating junction temperature range			-65 to +150	°C	
Storage temperature range			-65 to +150	°C	
Lead temperature 3.2 mm from case for 10 seconds			T _L 250		

NOTES: 1. This value applies for $t_p \le 0.3$ ms, duty cycle $\le 10\%$.

- 2. Derate linearly to 150°C case temperature at the rate of 0.64 W/°C.
- 3. Derate linearly to 150°C free air temperature at the rate of 28 mW/°C.
- 4. This rating is based on the capability of the transistor to operate safely in a circuit of: L = 20 mH, $I_{B(on)}$ = 0.4 A, R_{BE} = 100 Ω , $V_{BE(off)}$ = 0, R_{S} = 0.1 Ω , V_{CC} = 20 V.



TIP33, TIP33A, TIP33B, TIP33C NPN SILICON POWER TRANSISTORS

JULY 1968 - REVISED MARCH 1997

electrical characteristics at 25°C case temperature

PARAMETER		TEST CONDITIONS			MIN	TYP	MAX	UNIT
V _{(BR)CEO}	Collector-emitter breakdown voltage	I _C = 30 mA (see Note 5)	I _B = 0	TIP33 TIP33A TIP33B TIP33C	40 60 80 100			V
I _{CES}	Collector-emitter cut-off current	$V_{CE} = 80 \text{ V}$ $V_{CE} = 100 \text{ V}$ $V_{CE} = 120 \text{ V}$ $V_{CE} = 140 \text{ V}$	$V_{BE} = 0$ $V_{BE} = 0$ $V_{BE} = 0$ $V_{BE} = 0$	TIP33 TIP33A TIP33B TIP33C			0.4 0.4 0.4 0.4	mA
I _{CEO}	Collector cut-off current	$V_{CE} = 30 \text{ V}$ $V_{CE} = 60 \text{ V}$	$I_{B} = 0$ $I_{B} = 0$	TIP33/33A TIP33B/33C			0.7 0.7	mA
I _{EBO}	Emitter cut-off current	V _{EB} = 5 V	I _C = 0				1	mA
h _{FE}	Forward current transfer ratio	$V_{CE} = 4 V$ $V_{CE} = 4 V$	$I_C = 1 A$ $I_C = 3 A$	(see Notes 5 and 6)	40 20		100	
V _{CE(sat)}	Collector-emitter saturation voltage	$I_B = 0.3 \text{ A}$ $I_B = 2.5 \text{ A}$	$I_C = 3 A$ $I_C = 10 A$	(see Notes 5 and 6)			1 4	V
V_{BE}	Base-emitter voltage	$V_{CE} = 4 V$ $V_{CE} = 4 V$	$I_C = 3 A$ $I_C = 10 A$	(see Notes 5 and 6)			1.6 3	٧
h _{fe}	Small signal forward current transfer ratio	V _{CE} = 10 V	I _C = 0.5 A	f = 1 kHz	20			
h _{fe}	Small signal forward current transfer ratio	V _{CE} = 10 V	I _C = 0.5 A	f = 1 MHz	3			

NOTES: 5. These parameters must be measured using pulse techniques, t_p = 300 μ s, duty cycle \leq 2%.

thermal characteristics

PARAMETER			TYP	MAX	UNIT
$R_{\theta JC}$	Junction to case thermal resistance			1.56	°C/W
$R_{\theta JA}$	Junction to free air thermal resistance			35.7	°C/W

resistive-load-switching characteristics at 25°C case temperature

Ī		PARAMETER	TEST CONDITIONS †			MIN	TYP	MAX	UNIT
ĺ	t _{on}	Turn-on time	I _C = 6 A	$I_{B(on)} = 0.6 A$	$I_{B(off)} = -0.6 A$		0.6		μs
ĺ	t _{off}	Turn-off time	$V_{BE(off)} = -4 V$	$R_L = 5 \Omega$	$t_p = 20 \ \mu s, \ dc \le 2\%$		1		μs

 $^{^{\}dagger} \ \ \mbox{Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.}$

PRODUCT INFORMATION

^{6.} These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

TYPICAL CHARACTERISTICS

TYPICAL DC CURRENT GAIN COLLECTOR CURRENT TCS633AA 1000 $V_{CE} = 4 V$ T_C = 25°C $t_p = 300 \mu s$, duty cycle < 2%h_{FE} - DC Current Gain 100 10 1.0 0.01 0.1 1-0 10 I_c - Collector Current - A

COLLECTOR-EMITTER SATURATION VOLTAGE

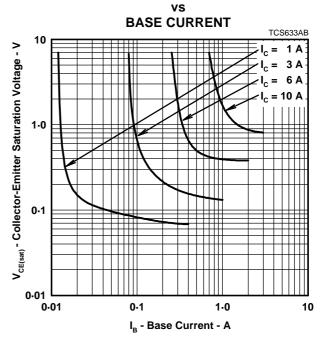


Figure 1. Figure 2.



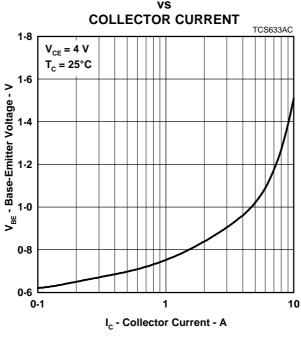
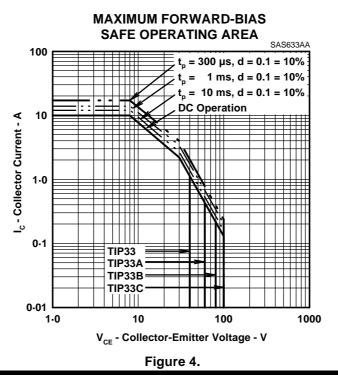


Figure 3.

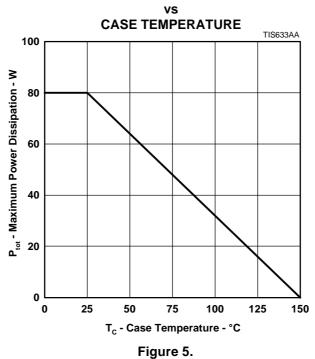


MAXIMUM SAFE OPERATING REGIONS



THERMAL INFORMATION

MAXIMUM POWER DISSIPATION



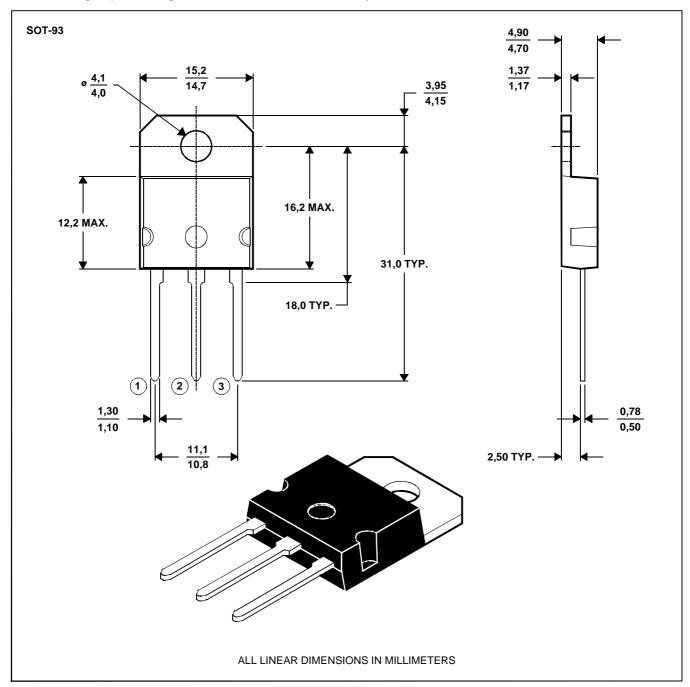
PRODUCT INFORMATION

MECHANICAL DATA

SOT-93

3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTE A: The centre pin is in electrical contact with the mounting tab.

MDXXAW



TIP33, TIP33A, TIP33B, TIP33C NPN SILICON POWER TRANSISTORS

JULY 1968 - REVISED MARCH 1997

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